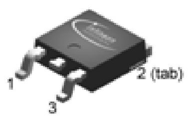
OptiMOS[TM] Power-Transistor

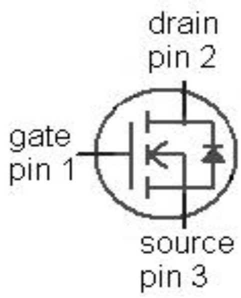
Features

- Optimized for synchronous rectification
- 100% avalanche tested
- Superior thermal resistance
- N-channel, normal level
- Qualified according to JEDEC[1]) for target applications
- Pb-free lead plating; RoHS compliant
- Halogen-free according to IEC61249-2-21

Product Summary

V_{DS}	60	V
$R_{DS(on),max}$	2.5	mΩ
I_D	90	A
Q_{OSS}	81	nC
Q_G(0V..10V)	71	nC

Type	IPD025N06N
	
Package	TO-252-3
Marking	025N06N



Maximum ratings, at T_j=25 °C, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current	I_D	V_{GS}=10 V, T_C=25 °C	90	A
		V_{GS}=10 V, T_C=100 °C	90	
		V_{GS}=10 V, T_C=25 °C, R_{thJA} =50K/W	26	
Pulsed drain current[2])	$I_{D,pulse}$	T_C=25 °C	360	
Avalanche energy, single pulse[3])	E_{AS}	I_D=90 A, R_{GS}=25 Ω	210	mJ
Gate source voltage	V_{GS}		±20	V

[1]) J-STD20 and JESD22

[2]) See figure 3 for more detailed information

[3]) See figure 13 for more detailed information

[4]) Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm^2 (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.

Maximum ratings, at T_j=25 °C, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Power dissipation	P_{tot}	T_C=25 °C	167	W
		T_A=25 °C, R_{thJA}=50 K/W	3.0	
Operating and storage temperature	T_j, T_{stg}		-55 ... 175	°C
IEC climatic category; DIN IEC 68-1			55/175/56	

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Thermal characteristics						
Thermal resistance, junction - case	R_{thJC}		-	-	0.9	K/W
Device on PCB	R_{thJA}	minimal footprint	-	-	62	
		6 cm² cooling area[4)]	-	-	40	

Electrical characteristics, at T_j=25 °C, unless otherwise specified

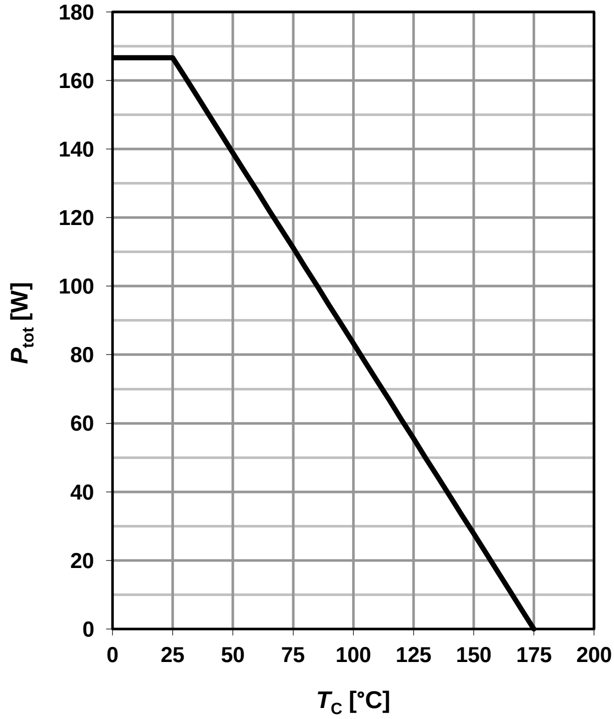
Parameter	Symbol	Conditions	min.	typ.	max.	Unit
Static characteristics						
Drain-source breakdown voltage	$V_{(BR)DSS}$	V_{GS}=0 V, I_D=1 mA	60	-	-	V
Gate threshold voltage	$V_{GS(th)}$	V_{DS}=V_{GS}, I_D=95 µA	2.1	2.8	3.3	
Zero gate voltage drain current	I_{DSS}	V_{DS}=60 V, V_{GS}=0 V, T_j=25 °C	-	0.5	1	µA
		V_{DS}=60 V, V_{GS}=0 V, T_j=125 °C	-	10	100	
Gate-source leakage current	I_{GSS}	V_{GS}=20 V, V_{DS}=0 V	-	10	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	V_{GS}=10 V, I_D=90 A	-	2.1	2.5	mΩ
		V_{GS}=6 V, I_D=22.5 A	-	2.7	3.8	
Gate resistance	R_G		-	1.7	2.6	Ω
Transconductance	g_{fs}	$\|V_{DS}\|>2\|I_D\|R_{DS(on)max}$, I_D=90 A	80	160	-	S

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Dynamic characteristics						
Input capacitance	C_{iss}	V_{GS}=0 V, V_{DS}=30 V, f=1 MHz	-	5200	6500	pF
Output capacitance	C_{oss}		-	1200	1500	
Reverse transfer capacitance	C_{rss}		-	48	96	
Turn-on delay time	$t_{d(on)}$	V_{DD}=30 V, V_{GS}=10 V, I_D=90 A, $R_{G,ext}$,ext=1.6 Ω	-	16	-	ns
Rise time	t_r		-	20	-	
Turn-off delay time	$t_{d(off)}$		-	34	-	
Fall time	t_f		-	12	-	
Gate Charge Characteristics[5]						
Gate to source charge	Q_{gs}	V_{DD}=30 V, I_D=90 A, V_{GS}=0 to 10 V	-	24	-	nC
Gate charge at threshold	$Q_{g(th)}$		-	14	-	
Gate to drain charge	Q_{gd}		-	13	17	
Switching charge	Q_{sw}		-	23	-	
Gate charge total	Q_g		-	71	83	
Gate plateau voltage	$V_{plateau}$		-	4.7	-	V
Gate charge total, sync. FET	$Q_{g(sync)}$	V_{DS}=0.1 V, V_{GS}=0 to 10 V	-	62	-	nC
Output charge	Q_{oss}	V_{DD}=30 V, V_{GS}=0 V	-	81	-	
Reverse Diode						
Diode continuous forward current	I_S	T_C=25 °C	-	-	90	A
Diode pulse current	$I_{S,pulse}$		-	-	360	
Diode forward voltage	V_{SD}	V_{GS}=0 V, I_F=90 A, T_j=25 °C	-	1.0	1.2	V
Reverse recovery time	t_{rr}	V_R=30 V, I_F=I_S, di_F/dt=100 A/µs	-	83	133	ns
Reverse recovery charge	Q_{rr}		-	105		nC

[5] See figure 16 for gate charge parameter definition

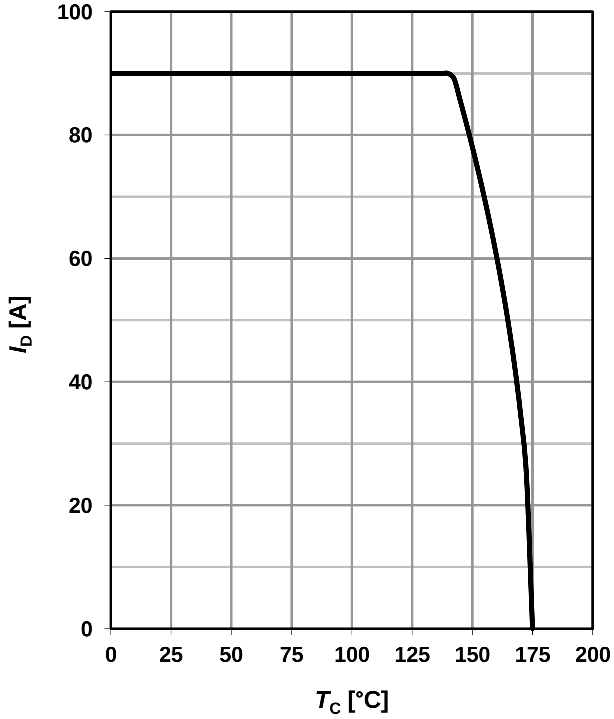
1 Power dissipation

P_{tot}=f(T_C)



2 Drain current

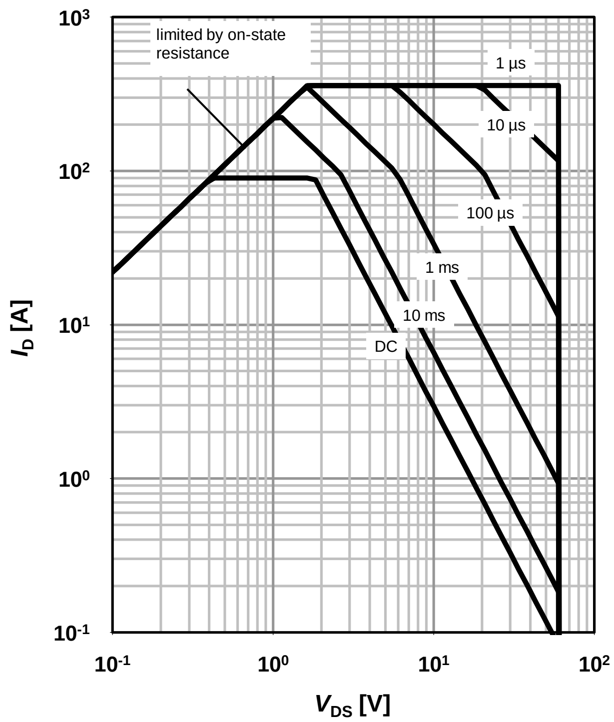
I_D=f(T_C); V_{GS}≥10 V



3 Safe operating area

I_D=f(V_{DS}); T_C=25 °C; D=0

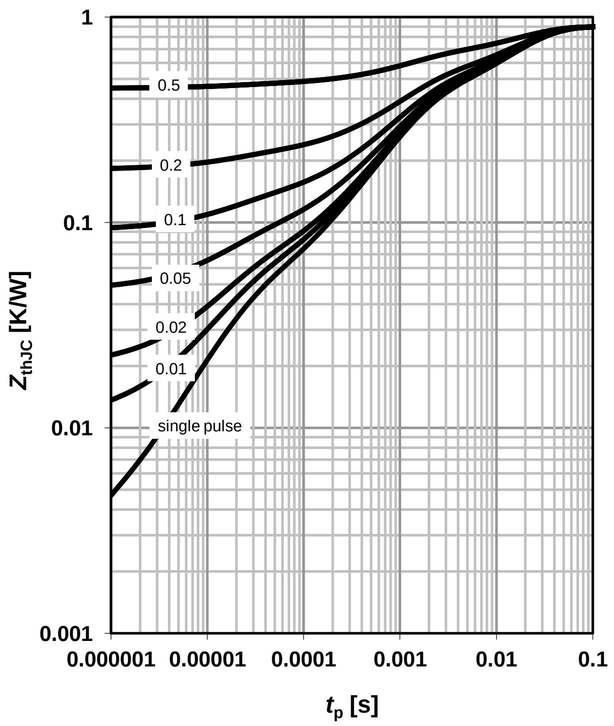
parameter: t_p



4 Max. transient thermal impedance

Z_{thJC}=f(t_p)

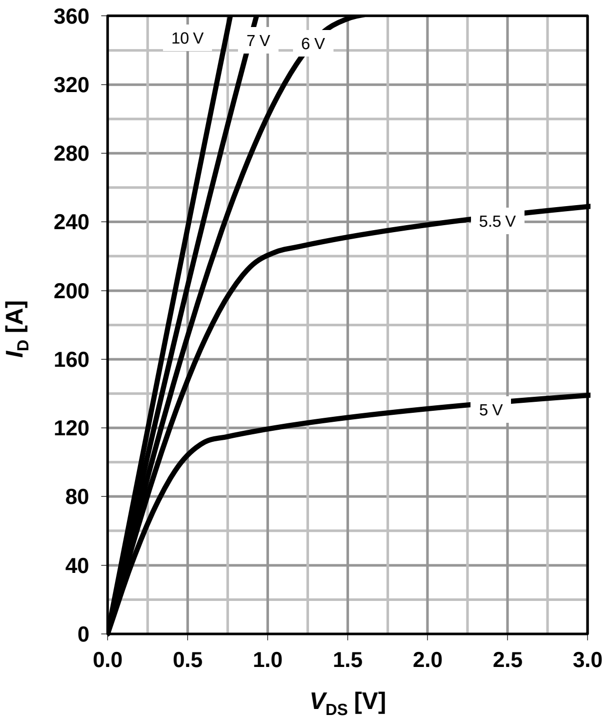
parameter: D=t_p/T



5 Typ. output characteristics

I_D=f(V_{DS}); T_j=25 °C

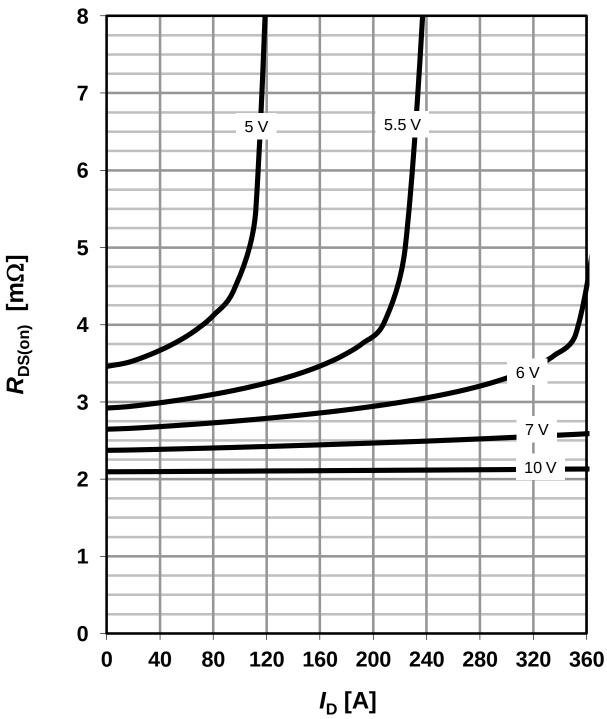
parameter: V_{GS}



6 Typ. drain-source on resistance

$R_{DS(on)}$=f(I_D); T_j=25 °C

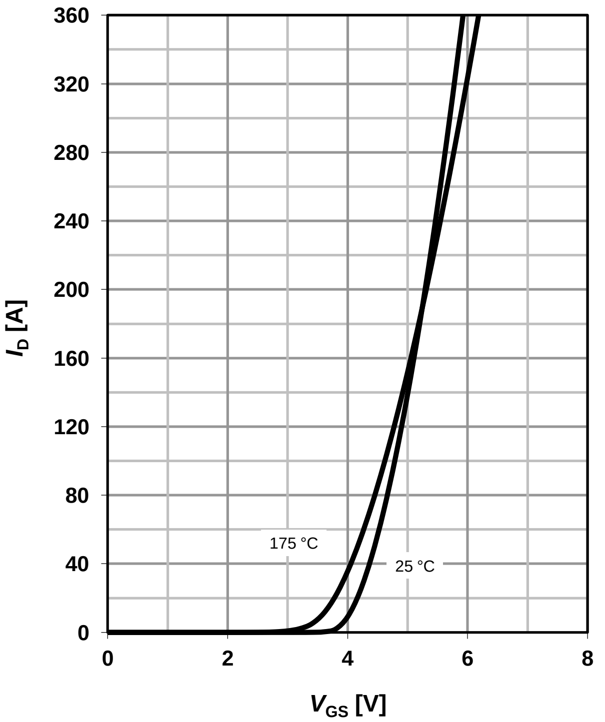
parameter: V_{GS}



7 Typ. transfer characteristics

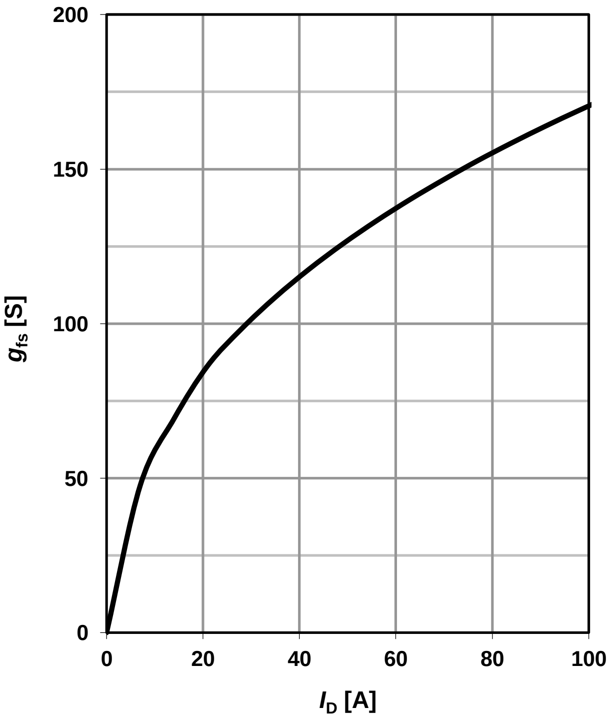
I_D=f(V_{GS}); |V_{DS}|>2|I_D|$R_{DS(on)max}$

parameter: T_j



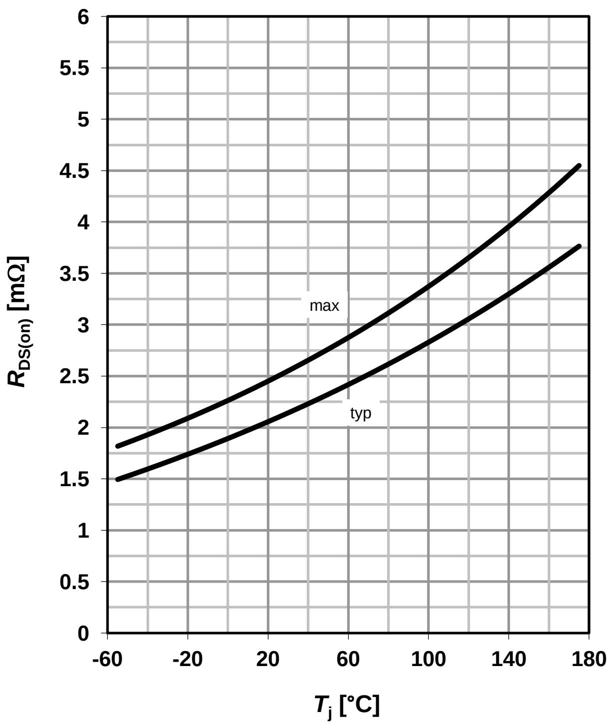
8 Typ. forward transconductance

g_{fs}=f(I_D); T_j=25 °C



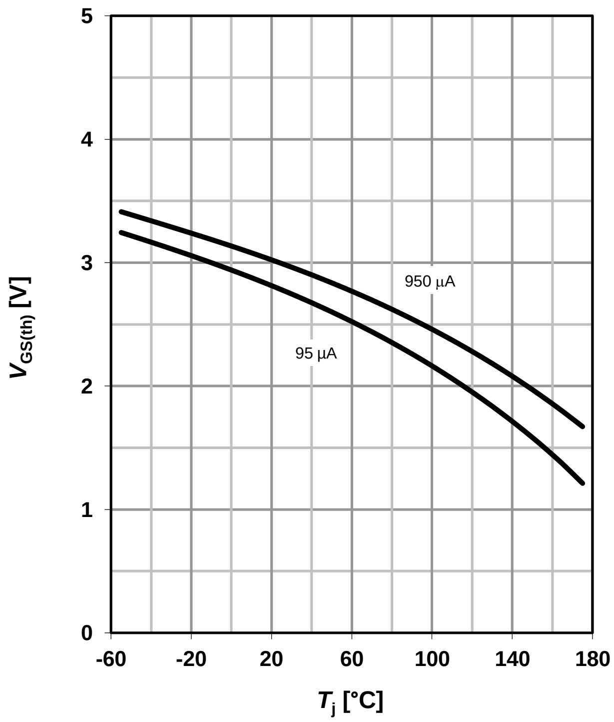
9 Drain-source on-state resistance

$R_{DS(on)}$=f(T_j); I_D=90 A; V_{GS}=10 V



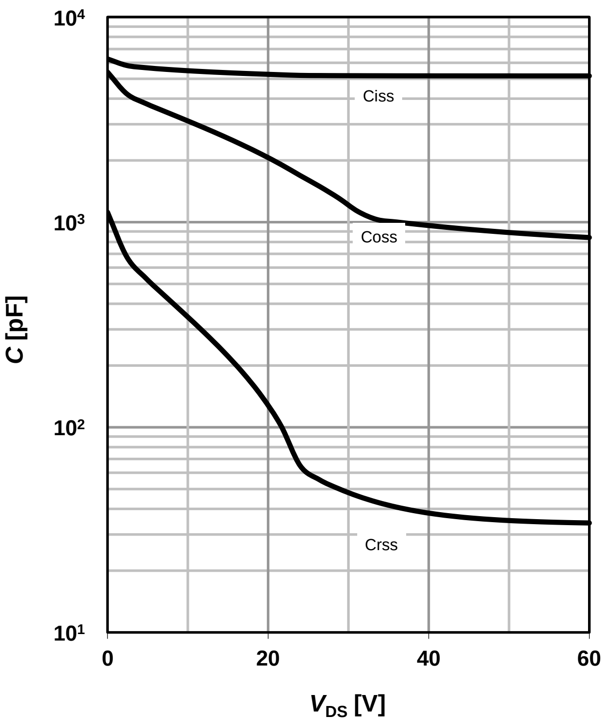
10 Typ. gate threshold voltage

$V_{GS(th)}$=f(T_j); V_{GS}=V_{DS}



11 Typ. capacitances

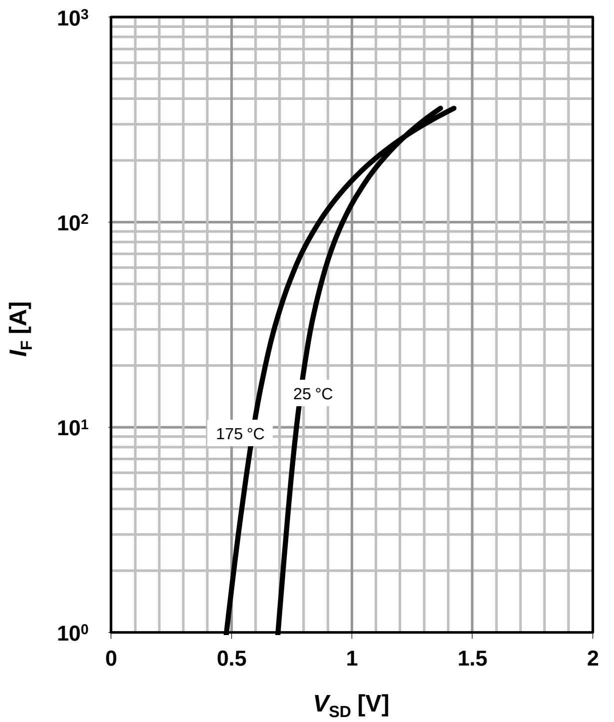
C=f(V_{DS}); V_{GS}=0 V; f=1 MHz



12 Forward characteristics of reverse diode

I_F=f(V_{SD})

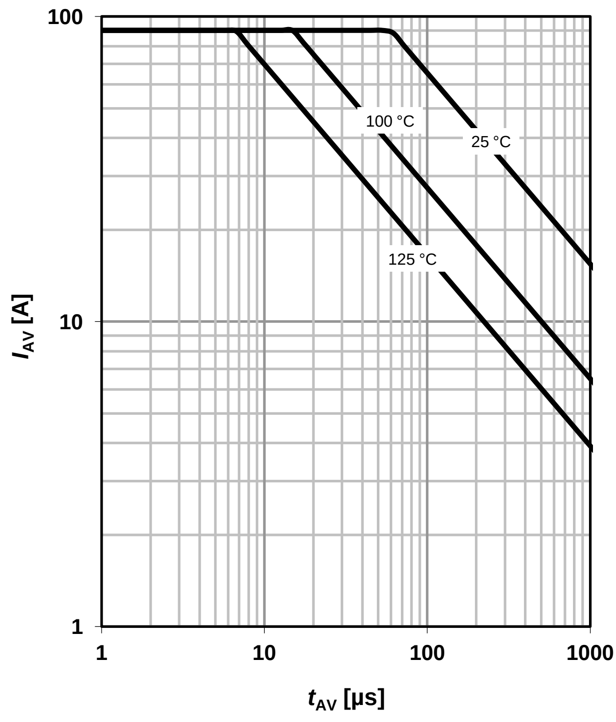
parameter: T_j



13 Avalanche characteristics

I_{AS}=f(t_{AV}); R_{GS}=25 Ω

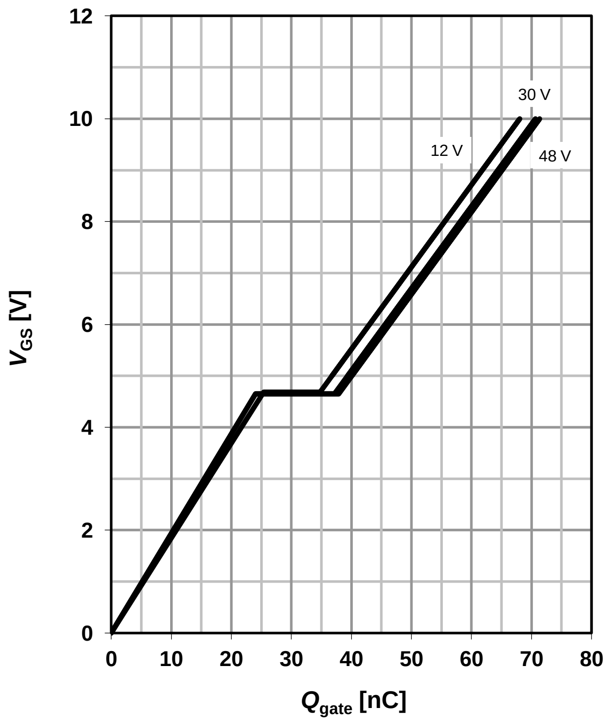
parameter: $T_{j(start)}$



14 Typ. gate charge

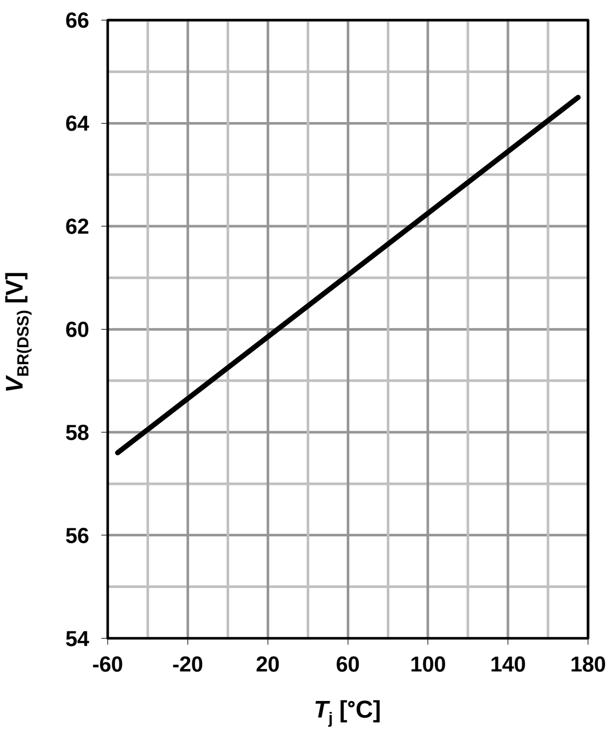
V_{GS}=f(Q_{gate}); I_D=90A pulsed

parameter: V_{DD}

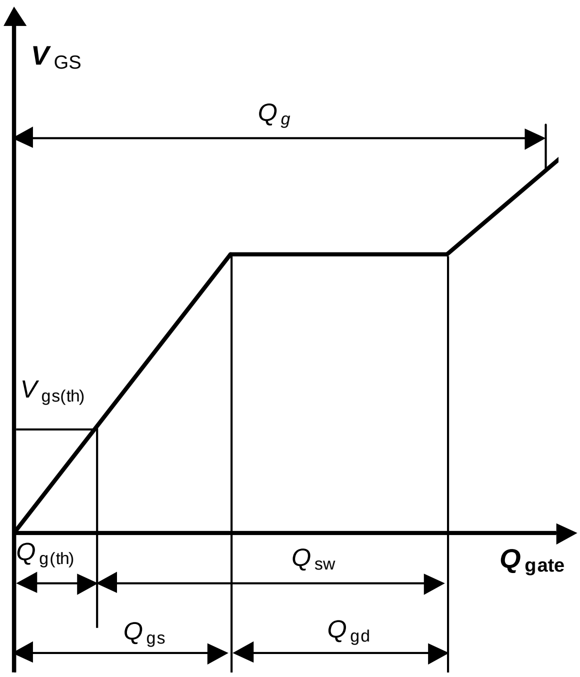


15 Drain-source breakdown voltage

$V_{BR(DSS)}$=f(T_j); I_D=1 mA

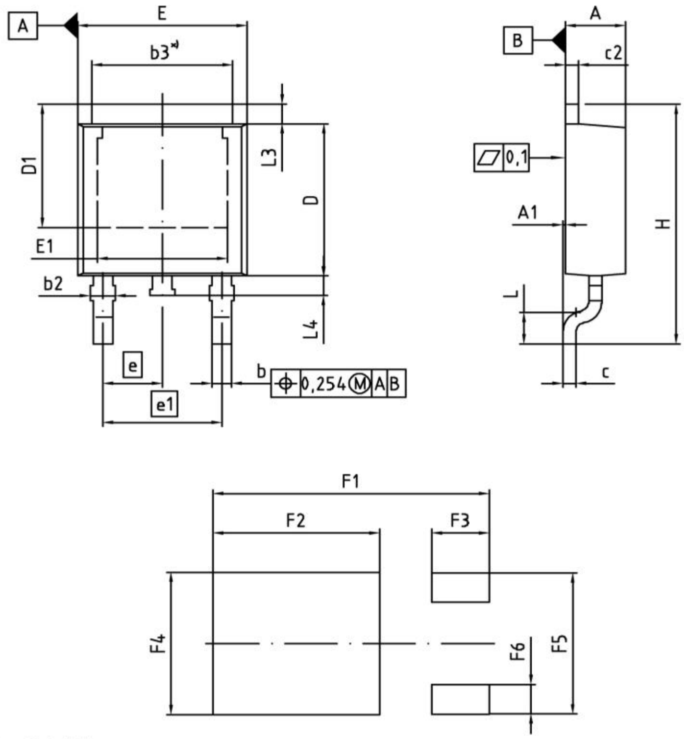


16 Gate charge waveforms



Package Outline

TO252-3 (DPAK)



*) mold flash not included

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.16	2.41	0.085	0.095
A1	0.00	0.15	0.000	0.006
b	0.64	0.89	0.025	0.035
b2	0.65	1.15	0.026	0.045
b3	5.00	5.50	0.197	0.217
c	0.46	0.60	0.018	0.024
c2	0.46	0.98	0.018	0.039
D	5.97	6.22	0.235	0.245
D1	5.02	5.84	0.198	0.230
E	6.40	6.73	0.252	0.265
E1	4.70	5.21	0.185	0.205
e	2.29 (BSC)		0.090 (BSC)	
e1	4.57		0.180	
N	3		3	
H	9.40	10.48	0.370	0.413
L	1.18	1.70	0.046	0.067
L3	0.90	1.25	0.035	0.049
L4	0.51	1.00	0.020	0.039
F1	10.60		0.417	
F2	6.40		0.252	
F3	2.20		0.087	
F4	5.80		0.228	
F5	5.76		0.227	
F6	1.20		0.047	

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